

IC Sockets: Market Research Report

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Abstracts

This report analyzes the Global market for IC Sockets in US\$ Million by the following product segments: Dual In-Line Memory Module Sockets, Production Sockets, Test/Burn-in Sockets, and Others.

Regional IC Sockets markets are analyzed as a consolidated whole with no granular level breakup offered by product group/segment.

Annual estimates and forecasts are provided for the period 2006 through 2015.

The report profiles 44 companies including many key and niche players such as 3M Company, Aries Electronics, Inc., Chupond Precision Co., Ltd., Enplas Corporation, FCI, Foxconn Technology Group, Johnstech International Corporation, Loranger International Corporation, Mill-Max Mfg. Corporation, Molex, Inc., Plastronics Socket Company, Inc., Sensata Technologies B.V., Tyco Electronics Ltd., Win Way Technology Co., Ltd., and Yamaichi Electronics Co., Ltd.

Market data and analytics are derived from primary and secondary research.

Company profiles are mostly extracted from URL research and reported select online sources.

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Ironwood Electronics Introduces New QFN Socket
Ironwood Electronics Launches High Performance BGA Socket
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Plastronics Launches ES Socket System
Thermaltake Unveils New CPU Cooler with Multiple Sockets
Fujitsu Launches SMT DDR2 DIMM Socket

Emulation Unveils Novel Socket System
MIPS Technologies Unveils Novel Instruction Set and Cores
Aries Electronics Launches CSP/BallNest Hybrid Socket
MiniATE Systems Introduces ET 2300 Socket System
Sullins Connector Solutions Extends Insulation Displacement Connector Portfolio
Fujitsu Asia Introduces PRIMERGY Dual Socket S5 Series
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3M COMPANY (US)

Aries Electronics, Inc. (US)
Chupond Precision Co., Ltd. (Taiwan)
Enplas Corporation (Japan)
FCI (France)
Foxconn Technology Group (Taiwan)
Johnstech International Corporation (US)
Loranger International Corporation (US)
Mill-Max Mfg. Corporation (US)
Molex, Inc. (US)
Plastronics Socket Company, Inc. (US)
Sensata Technologies B.V. (The Netherlands)
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Market Analysis

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IV. COMPETITIVE LANDSCAPE

Total Companies Profiled: 44 (including Divisions/Subsidiaries - 46)

Region/CountryPlayers

The United States

Japan

Europe

France

Germany

The United Kingdom

Rest of Europe

Asia-Pacific (Excluding Japan)

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